



30V N-CHANNEL ENHANCEMENT MODE MOSFET

Product Summary

BV _{DSS}	R _{DS(ON)} Max	I _D T _A = +25°C
30V	$23m\Omega$ @ $V_{GS} = 10V$	6.6A
300	$30m\Omega$ @ $V_{GS} = 4.5V$	5.8A

Description

This new generation MOSFET is designed to minimize the on-state resistance (R_{DS(ON)}), yet maintain superior switching performance, making it ideal for high-efficiency power management applications.

Applications

- DC-DC Converters
- Power management functions
- Backlighting

Features and Benefits

- Low Input Capacitance
- Low On-Resistance
- Fast Switching Speed
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- Qualified to AEC-Q101 Standards for High Reliability
- PPAP Capable (Note 4)

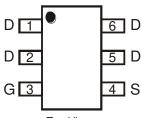
Mechanical Data

- Case: TSOT26
- Case Material: Molded Plastic, "Green" Molding Compound; UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish Tin Finish Annealed over Copper Leadframe. Solderable per MIL-STD-202, Method 208 @3
- Weight: 0.013 grams (Approximate)

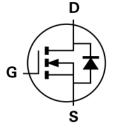
TSOT26







Top View Pin Configuration



Equivalent Circuit

Ordering Information (Note 5)

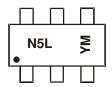
Part Number	Case	Packaging
DMN3026LVTQ-7	TSOT26	3,000/Tape & Reel
DMN3026LVTQ-13	TSOT26	10,000/Tape & Reel

Notes:

- 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.
- 2. See http://www.diodes.com/quality/lead free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and
- <1000ppm antimony compounds.</p>
 4. Automotive products are AEC-Q101 qualified and are PPAP capable. Automotive, AEC-Q101 and standard products are electrically and thermally the same, except where specified. For more information, please refer to http://www.diodes.com/quality/product_compliance_definitions/
- 5. For packaging details, go to our website at http://www.diodes.com/products/packages.html.



Marking Information



N5L = Product Type Marking Code YM = Date Code Marking Y = Year (ex: A = 2013) M = Month (ex: 9 = September)

Date Code Key

Year	2010	 2014	2015	2016	2017	2	2018	2019	2020	2021	2022
Code	Х	 В	С	D	Е		F	G	Н		J

Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code	1	2	3	4	5	6	7	8	9	0	N	D

Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Units			
Drain-Source Voltage	V_{DSS}	30	V			
Gate-Source Voltage	V_{GSS}	±20	V			
Continuous Drain Current (Note 7) Ves. 10V	Steady State	$T_A = +25^{\circ}C$ $T_A = +70^{\circ}C$	I _D	6.6 5.3	A	
Continuous Drain Current (Note 7) V _{GS} = 10V	t<10s	$T_A = +25^{\circ}C$ $T_A = +70^{\circ}C$	I _D	8.5 6.8	А	
Maximum Body Diode Forward Current (Note 7)	Is	3.0	Α			
Pulsed Drain Current (10µs pulse, duty cycle = 1%)	I _{DM}	35	Α			

Thermal Characteristics

Characteristic	Characteristic					
Total Power Dissipation (Note 6)	$T_A = +25$ °C	D-	1.2	W		
Total Fower Dissipation (Note 6)	$T_A = +70^{\circ}C$		0.8	٧٧		
Thermal Resistance, Junction to Ambient (Note 6)	Steady state	D	100	°C/W		
memai riesistance, sunction to Ambient (Note 6)	t<10s	$R_{ heta JA}$	60	°C/W		
Total Power Dissipation (Note 7)	$T_A = +25^{\circ}C$	P_D	1.5	W		
Total Fower Dissipation (Note 7)	$T_A = +70$ °C	FD	1.0			
Thermal Resistance, Junction to Ambient (Note 7)	Steady state	D	83	°C/W		
memai nesistance, sunction to Ambient (Note 1)	t<10s	$R_{ heta JA}$	50	°C/W		
Thermal Resistance, Junction to Case (Note 7)		$R_{ heta JC}$	14.5	°C/W		
Operating and Storage Temperature Range		T _{J,} T _{STG}	-55 to +150	°C		

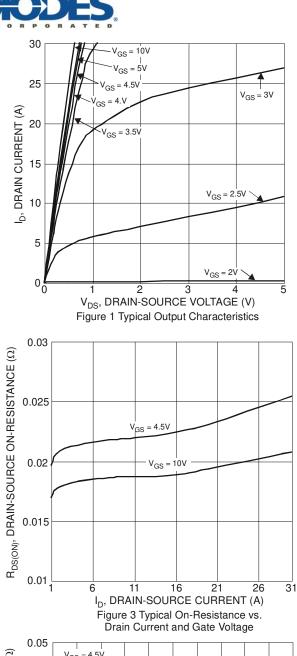


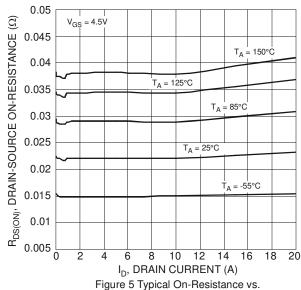
$\textbf{Electrical Characteristics} \ (@T_A = \underline{+25^{\circ}C}, \ unless \ \ otherwise \ specified.)$

Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition
OFF CHARACTERISTICS (Note 8)						
Drain-Source Breakdown Voltage	BV _{DSS}	30	_	_	V	$V_{GS} = 0V, I_D = 250\mu A$
Zero Gate Voltage Drain Current	I _{DSS}	_	_	1.0	μΑ	$V_{DS} = 30V, V_{GS} = 0V$
Gate-Source Leakage	I _{GSS}	_	_	±100	nA	$V_{GS} = \pm 20V, V_{DS} = 0V$
ON CHARACTERISTICS (Note 8)						
Gate Threshold Voltage	$V_{GS(th)}$	1.0	1.5	2.0	V	$V_{DS} = V_{GS}$, $I_D = 250 \mu A$
Static Drain-Source On-Resistance	D	_	19	23	mΩ	$V_{GS} = 10V, I_D = 6.5A$
Static Drain-Source On-nesistance	R _{DS(ON)}	_	22	30	11122	$V_{GS} = 4.5V, I_D = 6.0A$
Diode Forward Voltage	V_{SD}	_	0.7	1.2	V	V _{GS} = 0V, I _S = 1.0A
DYNAMIC CHARACTERISTICS (Note 9)						
Input Capacitance	Ciss		643	_		V _{DS} = 15V, V _{GS} = 0V f = 1.0MHz
Output Capacitance	Coss	_	65	_	pF	
Reverse Transfer Capacitance	C_{rss}	_	49	_		
Gate Resistance	Rg	_	2.5	_	Ω	$V_{DS} = 0V, V_{GS} = 0V, f = 1.0MHz$
Total Gate Charge (V _{GS} = 4.5V)	Q_g	_	5.7	_		
Total Gate Charge (V _{GS} = 10V)	Q_g	_	12.5	_	nC	V _{DS} = 15V, I _D = 4.0A
Gate-Source Charge	Q_{gs}	_	1.7	_	110	V _{DS} = 15V, I _D = 4.0A
Gate-Drain Charge	Q_{gd}	_	1.8	_		
Turn-On Delay Time	t _{D(on)}	_	2.2	_		
Turn-On Rise Time	t _r	_	2.5	_	nS	$V_{GS} = 10V, V_{DD} = 15V, R_G = 6.0\Omega,$
Turn-Off Delay Time	t _{D(off)}	_	12.1	_	110	I _D = 6.5A
Turn-Off Fall Time	tf	_	3.0	_		
Body Diode Reverse Recovery Time	t _{rr}	_	6.5	_	nS	I _F = 6.5A, dI/dt = 100A/μs
Body Diode Reverse Recovery Charge	Q _{rr}		1.7	_	nC	$I_F = 6.5A$, $dI/dt = 100A/\mu s$

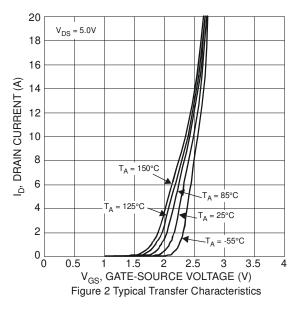
- 6. Device mounted on FR-4 substrate PC board, 2oz copper, with minimum recommended pad layout.
 7. Device mounted on FR-4 substrate PC board, 2oz copper, with 1-inch square copper plate.
 8. Short duration pulse test used to minimize self-heating effect.
 9. Guaranteed by design. Not subject to product testing.

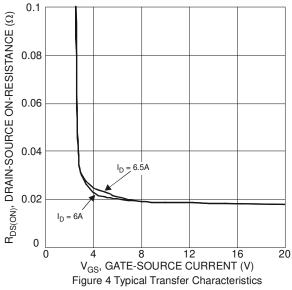


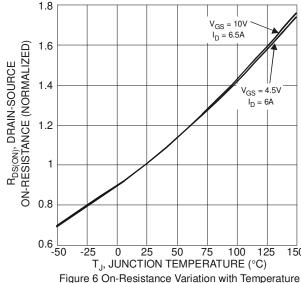




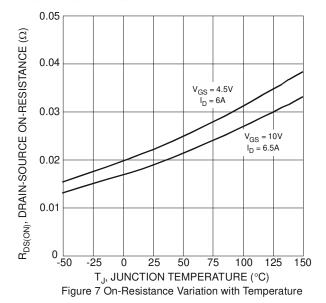
Drain Current and Temperature

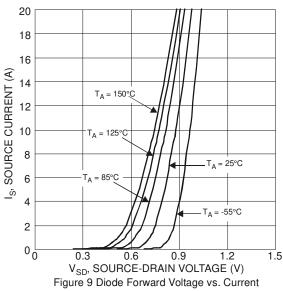


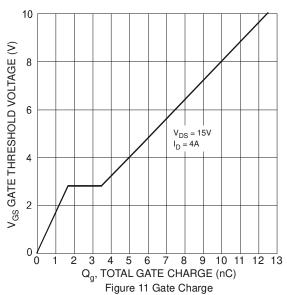












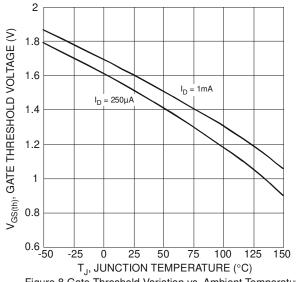
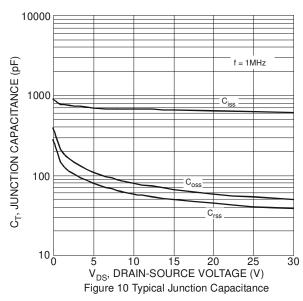
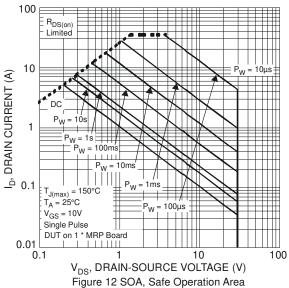
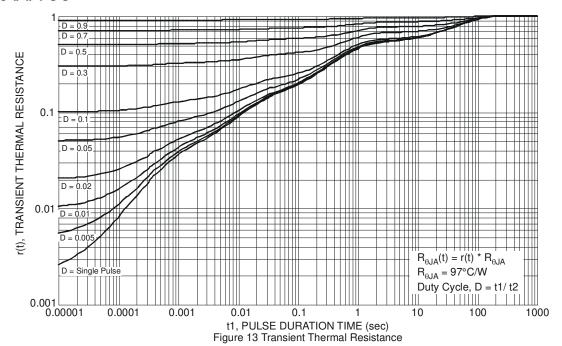


Figure 8 Gate Threshold Variation vs. Ambient Temperature







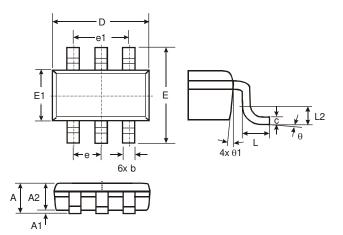




Package Outline Dimensions

Please see AP02002 at http://www.diodes.com/datasheets/ap02002.pdf for the latest version.

TSOT26

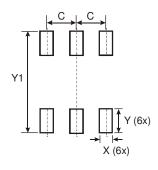


	TSC	T26					
Dim	Min	Max	Тур				
Α		1.00	_				
A1	0.01	0.10	_				
A2	0.84	0.90	_				
D		_	2.90				
Е			2.80				
E1	_	_	1.60				
b	0.30	0.45	_				
С	0.12	0.20	_				
е		-	0.95				
e1		-	1.90				
L	0.30	0.50	_				
L2			0.25				
θ	0°	8°	4°				
θ1	4°	12°	_				
All Dimensions in mm							

Suggested Pad Layout

Please see AP02001 at http://www.diodes.com/datasheets/ap02001.pdf for the latest version.

TSOT26



Dimensions	Value (in mm)
C	0.950
Х	0.700
Υ	1.000
Y1	3.199



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